The Valley Megaphone

Newsletter of the Institute of Electrical and Electronics Engineers, Inc., Phoenix Section

June 2011,
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IEEE Phoenix Section on-line updates can be found at http://ewh.ieee.org/r6/phoenix/ and on LinkedIn at:
http://www.linkedin.com/groups?gid=2765918
Please send announcements for the *Valley Megaphone* to Surinder Tuli at surinder.tuli@gmail.com and to Russ Kinner at r.kinner@ieee.org for inclusion in the Section Calendar.

The IEEE Banquet pictures are up, see http://ewh.ieee.org/r6/phoenix/AnnualBanquet.htm

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The Valley Megaphone is the newsletter of the Phoenix Section of the Institute of Electrical and Electronics Engineers. It is published monthly and reaches about 4000 members. Submit articles, advertisements, and announcements to Surinder Tuli at the above email address. Deadline for announcements and dvertisements is the third Friday of the month prior to publication. Advertising Rates: Full page: $200, 3/4page: $125, ½ page: $75, 1/3 page: $50, 1/4 page: $25. Change of address/email? Call toll free 1-800-678-IEEE. Please allow 6-8 weeks. Section Web Page is: http://ewh.ieee.org/r6/phoenix/

U – News

(for Student Members)

Updates of Student Advisors and Committee Members

Each Student Branch noted on the right side of this page should review current information on Advisors and Student Committee Members and forward to my attention within this week, as we are reviewing contacts for reporting and activities including Student Monthly Meetings.

Nick Leonardi
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Student Activities Chair

Student Branches

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ASU Polytechnic
Chair: TBD
Advisor: TBD

DeVry, Phoenix
Chair: TBD
Advisor: Diane Smith
dsmith2@devry.edu

DeVry, Computer Society
Chair: TBD
Advisor: Diane Smith
dsmith2@devry.edu

NAU, Engineering
Chair: TBD
Advisor: Niranjan Venkatraman
v.niranjan@ieee.org

Embry-Riddle, Prescott
Chair: Tim Lemm
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Advisor: John E. Post
postj@erau.edu

U – Newsbytes

- ASU Polytechnic is currently seeking Advisor for the Student Branch. Please email Nick (at email address above) with Recommendations.

Start your own MicroMouse and compete for cash prizes!

- The Section has a full tournament sized MicroMouse maze. Funding for your project may be available. For details contact the Section Student Activities Chair, Nick Leornardi at nleonardi@ieee.org.
- View pictures from the MicroMouse contest at the Southwest Area Spring 2010 meeting at http://picasaweb.google.com/ieeegoldphx/2010IEEESWASpringMeeting (photography by David Huerta, GOLD Affinity Group Chair) check with Nick

Phoenix Chapter of IEEE Signal Processing Society and Communications Society

Thanks to all of the attendees who have made this year's technical meetings so successful. More to come in the coming months...

Please contact Chapter Chair David Frakes (dfrakes@asu.edu) to volunteer or propose a speaker for upcoming meetings.

IEEE Components, Packaging and Manufacturing Technology Society Phoenix Chapter

Wednesday, June 15th, 2011 at 6 PM

Flip Chip Technology – A Status Update

Dr. Dev Gupta

Chief Technical Officer

Advanced Packaging & Systems Technology Laboratories LLC

Scottsdale, Arizona 85262

ABSTRACT:

Over the past 15 years the application of Flip Chip interconnects technology has grown at a CAGR of 20 to 30 % driven by its advantages for high performance computing. Recently, handheld systems such as smart phones and tablets have also reached the performance threshold where flip chip becomes indispensable, thus expanding its application space. Current volume for flip chip technology is estimated to exceed $10 billion/ year, nearly a third of the total A&T market worldwide. Flip Chip related activity including R&D has now inevitably migrated from pioneer IDMs to leading OSATs and several variations of Flip Chip technology are now being offered by them for emerging applications like Smart Phones and 3D die stacks using TSVs. This talk will review several aspects of flip chip technology including the traditional solder bump flip chip technology, chip package interaction issues in migrating to Pb-free solder bumps, low-k and ultra low-k dielectrics and various pillar bump technologies including the Cu-pillar bumps. Theoretical understanding of electro-migration related reliability issues in Cu pillar interconnect will also be discussed.

BIOGRAPHY:

Dr. Dev Gupta is Chief Technical Officer at APSTL LLC, Scottsdale, AZ, a company specialized in turn-key engineering of Fabs and Advanced Packaging facilities. APSTL has developed Column Bump Flip Chip technology, set up wafer bumping and assembly lines and new substrate technologies to minimize chip package interaction, for its customers in the US and Japan. Dr. Gupta has been active in the Advanced Packaging field for over 20 years mostly in the flip chip area. At Motorola, he developed one of the earliest electroplated solder bump technology and assembly robots that went into ASIC production in the early 1990s. He also developed world's first column bump flip chip technology that improved the packaging of GaAs power amplifiers. At Intel he managed the development and high volume manufacturing of organic substrates for flip chip. Dr. Gupta has been granted 13 US patents and others are pending. He chaired a very successful IEEE Workshop on Packaging needs for portable systems. He holds a PhD in Materials Science and Mathematics from the University of Arizona, Tucson.

Date: Wednesday, Wednesday June 15th, 2011

Location: Group Conference Room, Freescale Semiconductor, Inc., 2100 E. Elliot Rd. Tempe, AZ. Enter the facility through the Main (South) lobby in building 94, by the flag poles; you will be escorted to the meeting venue.

Time: 5:30–6:00 Social/Refreshments, 6:00–7:00 Presentation, 7:00 Dinner
(Pizza and Soda will be provided by the IEEE CPMT Phoenix Chapter)

IEEE members and non-members are all welcome to attend. Those who plan to attend should be at the facility entrance no later than 6:00 pm, as there will be no escorts available after that.

For more information, please contact any of the following CPMT officers:

Vivek Gupta (480) 413-5849
Guat Li Chew (480) 552-1128
Vasu Atluri (480) 227-8411
Samir Pandey (480) 552-7502

IEEE Power and Energy Society

Phoenix Chapter

News and Announcements:

- Want to know more about IEEE PES? Watch this video: http://www.youtube.com/watch?v=BRKM4lpo_tk
- IEEE PES Scholarships are available: http://www.ee-scholarship.org/

Schedule of Upcoming 2011 Events

Monthly Luncheon and Seminar

Luncheons on hold over summer
Next Date: Thursday, September 15th
Check the website for further information

IEEE Phoenix Section 70th Anniversary

Date: Saturday, June 11th
More information:
http://ewh.ieee.org/soc/pes/phoenix/phx70th.php

54th Annual IEEE PES Phoenix Chapter Golf Tournament!

Date: Saturday, September 24th
Location: Antelope Hills Golf Club, Prescott
Check the website for further information

More information regarding the IEEE PES Phoenix Chapter can be found at: http://ewh.ieee.org/soc/pes/phoenix/index.php

Phoenix Section Life Member Affinity Group

About IEEE Phoenix Section Life Member Affinity Group:

An IEEE member automatically becomes an IEEE "Life Member" status when at least 65 years of age and the sum of your current age and years of membership is 100. For more details use the link
http://www.ieee.org/web/volunteers/mga/home/life_members_committee/index.html

Activities: Annual technical meetings scheduled in February, May, October, and December. Elections are held at the December meeting.

Future Technical Meetings:

- Tuesday, October 11, 2011 SRP PERA CLUB
- Tuesday, December 6, 2011 SRP PERA CLUB

Officers:

Chair	A. Barry Cummings	*Barry.Cummings@srpnet.com*
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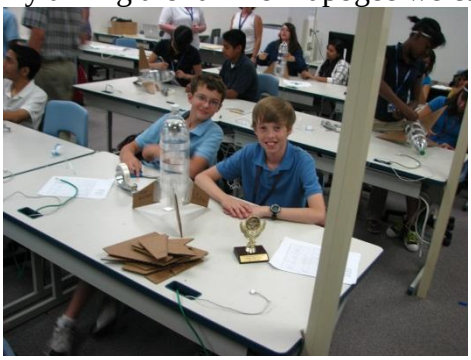
Past Chair	C Bruce Johnson	*cbj@johnsonscientificgroup.com*

Teacher In Service Program / Engineers In The Classroom

We finished the 2010 / 2011 school year last week with a "Rockets" class at Connolly Middle School in Tempe for the 7th grade. A fitting end to the year! Prior to that we had done two weeks at Fees Middle School in Tempe doing "Here comes The Sun" with the 6th grade. Over the past school year we have taught around 2500 students and we are already booked up for October and November, and part of May, in the 2011 / 2012 school year. This link: http://www.youtube.com/watch?v=UYzatTm-Y-k will show you a short video of the Rockets class we did at Orangewood Middle School in Washington District earlier in the year; it is a good example of how our lessons go. Some pictures follow:

By timing the fall from apogee we calculated rockets were going as high as 80 - 125 meters.



This month three of us will be putting on a "classical" TISP session with 46 teachers at the Biosphere, and three more will be supporting Kid Zone at their summer school.
A short while ago on April 6th, all those in EIC who have worked with Kid Zone until now were honored by the City of Tempe at their Volunteer Breakfast, and given a group award for outstanding volunteer service:

The young lady is Michael Doherty, an ASU civil engineering graduate who we support at Kid Zone. The EIC members are: Tom Innes, Stu Wecker, John Fitch, John Purchase, Ray Heinle , Charles Slivinsky; not present: Roy Zaborowski, Richard Meyer, Les Holland, Thad Enloe.

Women In Engineering Affinity Group (WIE)

The IEEE Phoenix Section supports establishing a local **Women in Engineering (WIE) Affinity Group**. Before moving forward with the process, we would like to ascertain the level of interest in the area of the Phoenix Section. If you see value in having this group and if you would be interested in participating in local WIE Affinity Group activities, please contact Shamala Chickamenahalli (shamala@ieee.org), Lesley Polka (lesley.a.polka@intel.com) and Diane Watkins (diane.watkins@srpnet.com).

The IEEE WIE Affinity Group's mission is to inspire, engage, encourage and empower IEEE women worldwide with a vision of creating a community of IEEE women and men innovating the world of tomorrow. More information about IEEE WIE can be found at their website:
http://www.ieee.org/membership_services/membership/women/women_about.html

Looking forward to hearing from you,
Shamala, Lesley and Diane

IEEE Advancing Technology for Humanity

IEEE Phoenix Section Women in Engineering Affinity Group

IEEE Women in Engineering WIE

The IEEE Phoenix Section has submitted the paperwork to the national office to establish a a local **Women in Engineering (WIE) Affinity Group**. We held a kick-off event on May 20, 2011, at the Embassy Suites – Biltmore in Phoenix in conjunction with the 2011 international IEEE WIE committee meeting held the same weekend at the same venue. Our local group was pleased to welcome an audience of about 50 that included IEEE WIE committee members from around the world as well many local woman and men interested in our theme for the evening: "Together We Lead: Locally, Nationally, and Internationally." Our three speakers for the evening were:

- Dr. Ramalatha Marimuthu, 2011 IEEE WIE Committee Chair
    - Dr. Jan Belt, Chairman, Agilesys
    - Dr. Karen Panetta, IEEE Fellow & Editor-in-Chief of the IEEE WIE Magazine

They inspired the audience with their experiences in creating positive change in their communities through science, engineering and technology.

The local IEEE Phoenix WIE Affinity Group is presently planning its Fall 2011 activities and events. If you would be interested in participating in future local WIE Affinity Group activities and would like to be added to our distribution list, please contact one of the members of our organizing committee: Shamala Chickamenahalli (shamala@ieee.org), Lesley Polka (lesley.a.polka@intel.com) or Diane Watkins (diane.watkins@srpnet.com).

The IEEE WIE Affinity Group's mission is to inspire, engage, encourage and empower IEEE women worldwide with a vision of creating a community of IEEE women and men innovating the world of tomorrow. More information about IEEE WIE can be found at their website: http://www.ieee.org/membership_services/membership/women/women_about.html

IEEE Computer Society

Phoenix Chapter of the IEEE Computer Society
June, 2011

News

- The May meeting was well attended and featured presentations by Dr. Brad Morantz on using contemporary multi-core processor platforms to more efficiently solve complex mathematical problems and David Surrett on the creation and testing of avionics software for the aircraft industry.

Future Events

We continue with our bi-monthly schedule for 2011:

- July 6 – Chapter meeting, DeVry University; speaker TBD
- September 7 – Chapter meeting, DeVry University; speaker TBD
- November 2 – Chapter meeting, DeVry University; speaker TBD

Meetings start at 6:00 pm with networking and light refreshments in the courtyard followed by the presentation at 7:00 pm. DeVry University is located at 2149 W Dunlap Avenue, Phoenix.

Visit the CS Chapter website for the latest information: http://ewh.ieee.org/r6/phoenix/compsociety/.
For brief announcements regarding upcoming events we are also on Twitter: @IEEECS_PHX

If you would like to suggest a topic or speaker for any of our 2011 meetings, please contact one of the chapter officers:

Jerry Crow (jerry.crow@computer.org)
Brad Morantz (bradscientist@ieee.org)
Audrey Skidmore (askidmore@computer.org)
Diane Smith (sdianesmith@computer.org)

INSTITUTE OF ELECTRICAL AND ELECTRONIC ENGINEERS

WAVES AND DEVICES

PHOENIX CHAPTER

http://ewh.ieee.org/r6/phoenix/wad/

2011 Calendar

Date	Time	Location	Topic / Title / Status	Speaker	Affiliation
17-Jan	5:00 PM	Freescale	1) Electromagnetic Band Gap (EBG) Structures in Antenna Engineering: From Fundamentals to Recent Advances 2) Green" RFID and Wireless Sensor Nodes: The Final Step to Bridge Cognitive Intelligence, Nanotechnology and RF?	1) Dr. Yahya Rahmat-Samii 2) Dr. Manos Tentzeris	1) UCLA 2) Georgia Tech
18-Feb	4:00 PM	ASU GWC487	Miniaturized Directional Microphones and Microspeakers for Hearing Aids Applications	Dr. Junseok Chae	ASU
28-Feb	1:00 PM	ASU GWC487	Joint Meeting With SSCS: Technology Challenges of Integrated Voltage Regulators for Future Microprocessors and SOC's	Dr. Shamala A. Chickamenahalli	Intel
24-Mar	5:30 PM	ASU GWC487	Semiconductor Device Characterization and Failure Analysis	Dr. Dieter Schroder	ASU
18-Apr	1:30 PM	ASU	Analog-to-Digital Converters for Software-Definable Radios	Dr. Doug Garrity	Freescale
2-May	**6:00 PM**	**ASU**	**Modeling and Simulation of Submillimeter Wave Semiconductor Devices**	**Dr. Stephen Goodnick**	**ASU**
29-Jun	**6:00 PM**	**TBD**	**Radio Communications Systems on Next Generation Manned Space Vehicle**	**Mr. William Boger**	**General Dynamics**
July (TBD)	**TBD**	**TBD**	**Wide Band Gap Materials & Applications**	**Dr. Chuck Weitzel**	**Consultant**
Aug 18 (Tentative)	**TBD**	**TBD**	**Microwave topic**	**Dr. Jeremy Muldavin**	**MIT Lincoln Labs**
Sept (TBD)	**TBD**	**ASU**	**Antennas Topic**	**Dr. Constantine Balanis**	**ASU**

INSTITUTE OF ELECTRICAL AND ELECTRONIC ENGINEERS

WAVES AND DEVICES - Phoenix Chapter

Meeting Free & Open to Non-IEEE Members

6:00 PM, Wednesday, June 29th, 2011

Arizona State University
Goldwater Center, GWC487
650 E. Tyler Mall, Tempe, AZ

Radio Communications for Next Generation NASA Manned Spacecraft

Mr. William Boger
General Dynamics - AIS

Abstract

Although NASA's manned space program has evolved with the changes in political leadership, there continues to be a need for a new generation of manned space transportation systems to replace the retiring space shuttle fleet and provide access to the International Space Station (ISS). Although immediate needs are for near earth missions such as the ISS, NASA is aligning the design of its transportation system elements to allow for easy modifications for future lunar and deep space missions. These goals have resulted in the need for a communications system with some new and unique capabilities for the spacecraft being developed by Lockheed Martin for NASA. General Dynamics is developing a high reliability radio to fill these needs, and provide the flexibility required for the future using a software-programmable radio architecture. This presentation will provide some background and overview of the communications system and the new radio architecture and technologies being developed for NASA's manned space program.

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Biography

Mr. William Boger is a Member of the Technical Staff in Space Communications at General Dynamics AIS in Scottsdale, AZ. This part of General Dynamics was formerly part of Motorola Corporation and is the same engineering group that has been providing communications for the space program since the beginning. Mr. Boger was granted the BSEE degree from the University of North Dakota in 1979 and the MSEE with emphasis in communications systems from Arizona State University in 1992. Prior to General Dynamics, Mr. Boger has worked for Sperry Corporation and Motorola.

Date: **Thursday, June 29, 2011**

Time: **6:00 PM *Presentation*, Pizza will be served following the Seminar**

Location: Goldwater Center, GWC487, Arizona State University, 650 E. Tyler Mall, Tempe, AZ

For more information, contact:

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Haolu Xie (Chapter Publicity)	(480) 413-5644	haolu.xie@ieee.org

WAD Website: http://ewh.ieee.org/r6/phoenix/wad/

CALL FOR PAPERS

2011 BIPOLAR/BiCMOS CIRCUITS AND TECHNOLOGY MEETING

Atlanta, Georgia, USA

http://2011.ieee-bctm.org

Short Course: Sunday, October 9, 2011, Conference: Monday and Tuesday, October 10-11, 2011

The Bipolar/BiCMOS Circuits and Technology Meeting (BCTM) is a forum for technical communication focused on the needs and interests of the bipolar and BiCMOS community. Papers covering the design, performance, fabrication, testing and application of bipolar and BiCMOS integrated circuits, bipolar phenomena, and discrete bipolar devices are solicited. All papers must be suitable for a twenty-minute presentation. Text and figures must not have been presented at other conferences or published in any scientific or technical publications prior to BCTM.

Publication in the BCTM 2011 Proceedings does not preclude publication in an IEEE journal, and authors are encouraged to do so. A Special Issue of the *IEEE Journal of Solid-State Circuits* will include selected papers from BCTM 2011.

Papers are solicited in the following areas

ANALOG / DIGITAL CIRCUIT DESIGN: Analog ICs - Digital ICs - Mixed analog/digital ICs - Novel design concepts and methods - DACs and ADCs - Amplifiers - Integrated filters - Communications ICs - Sensors - Gate arrays - Cell libraries - Voltage references - Analog subsystems within a VLSI chip - Packaging of high-performance ICs. High-voltage ICs - Automotive electronics, disc drives, display drivers, power supplies, electric utility, medical electronics, motor controls, regulators, amplifiers, converters, aerospace electronics.

RADIO FREQUENCY CIRCUIT DESIGN: Low Noise Amplifiers - Automatic gain control - VCOs - Mixers – Active gyrators - Power amplifiers - RF DMOS-based circuits - Switches - Noise suppression techniques - Frequency synthesizers - Radio subsystems - Packaging of RF components - Designing with integrated passive components at RF frequencies - Millimeter-wave circuits and systems.

WIRELINE COMMUNICATIONS: LAN, WAN, FDDI, Ethernet, Metro, Fiber channel, SONET, ATM, ISDN, xDSL, optical data links - Power-line/phone-line networks - Cable modems, broadband circuits - MUX/DEMUX – Clock and data recovery - Error coding and correction - Crosspoint switches - Laser and modulator drivers - Preamplifiers - AGC amplifiers - Decision circuits - Equalizers - Optical networking ICs.

DEVICE PHYSICS: New device physics phenomena in Si, SiGe, and III-V devices - Device design issues and scaling limits - Hot electron effects and reliability physics - Transport and high field phenomena - Noise - Linearity/Distortion – Novel measurement techniques - Operation in extreme environments (low and high temperatures, radiation effects).

MODELING / SIMULATION: Improved BJT and HBT models - Behavioural modeling techniques - Parameter extraction methods and test structures - De-embedding techniques - RF and thermal simulation techniques - Modeling of passives, interconnect and packages - Statistical modeling - Device, process and circuit simulation. CAD/modeling of power devices, packaging of power devices, and ESD phenomena.

PROCESS TECHNOLOGY: Advances in processes and device structures demonstrating high speed, low power, low noise, high current, high voltage, etc. BiCMOS processes - Advanced process techniques – Si and Si-C homojunction bipolar/BiCMOS devices, III-V and SiGe heterojunction bipolar/BiCMOS devices. Manufacturing solutions related to Bipolar and BiCMOS yield improvements. Fabrication of high-performance passive components, including, MEMs. Process technology related to discrete and integrated bipolar/BiCMOS power devices, IGBT, RF power devices including DMOS. Wide bandgap bipolar devices (i.e. SiC, GaN, GaAs etc.) and related process technology.

STUDENT paper submissions are highly encouraged. Papers must be clearly marked as 'STUDENT SUBMISSION' in the abstract cover sheet to be eligible for the Best Student Paper Award.

If you know of people who may have a paper to contribute please bring this Call for Papers to their attention.

IMPORTANT DEADLINES FOR AUTHORS

Monday, May 2, 2011 Deadline for receipt of abstract and summary
Friday, June 10, 2011 Notification of acceptance to be sent by email
Friday, July 8, 2011 Final proceedings manuscript due

SUBMISSION AND CONTACT INFORMATION

Visit the conference website: http://2011.ieee-bctm.org, or contact:
Jan Jopke, Conference Manager, CCS Associates, 6611 Countryside Drive, Eden Prairie, MN 55346, USA
TEL: 1-952-934-5082, FAX: 1-952-934-6741 E-mail: ccsevents@comcast.net.

RFIC 2011

www.rfic2011.org

2011 IEEE Radio Frequency Integrated Circuits Symposium

Baltimore Convention Center
Baltimore, MD, USA
Sunday, June 5th, 2011 – Tuesday, June 7th, 2011

Topics related to original work in RFIC design, system engineering, system simulation, design methodology, RFIC circuits, fabrication, testing and packaging to support RF applications in areas such as: Cellular System ICs, Wireless Data System ICs, Wideband System ICs, Silicon mm-Wave ICs, Small-Signal Circuits, Large-Signal Circuits, Frequency Generation Circuits, RFIC Device Technologies, RFIC Testing, RFIC Modeling and CAD.

Image Courtesy of Ed Niehenke

Plenary Speakers

Dr. Samuel Sheng, Telegent Systems
"RF Coexistence – Challenges and Opportunities."

Mr. Ron Ruebusch, Avago Technologies
"3G to 4G Transition – Challenges and Opportunities."

Technical papers will be presented during oral sessions throughout Monday and Tuesday. There will be a total of 130 papers presented in 23 technical focused sessions. The technical program will conclude with the Interactive Forum session on Tuesday afternoon, which will feature 31 poster papers and the chance to speak directly with authors regarding their work.

Workshops (Sunday):
Introduction to GaN MMIC Design
Advancements and Challenges toward Radio-in-Package and Radio-on-Chip
Imaging at mm-Wave and Beyond
RF Bio-Medical Electronics and Sensors
Re-configurability Requirements for Multi-Standard Low-Power Operation
Advancements in Linear Power Amplifiers for Cellular Infrastructure
EMI Compliant Product Design Practices: Interference Analysis, Floor Planning, Grounding Strategies, Chip-Package-Board Co-Design
New Architectures for Digitized Receivers
Design for Manufacturability and Self-Testability of RFICs
Systems & Circuits for Sensing, Co-Existence, and Interference Mitigation in SDR and Cognitive Radios
Efficiency Enhancement Techniques of Power Amplifiers and Transmitters for Mobile Applications

Panels (Monday & Tuesday):
Software Defined Radios - Facts and Fantasies
What is the limit of multi-radio integration ... or rather, is it 'disintegration'?

Short Courses (sponsored by IMS):
Techniques and Realizations of Microwave and RF Filters
Nonlinear Dynamics and Stability Analysis/Design of Microwave Circuits

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Advance Program and Registration on-line: www.imaps.org/opto

IMAPS/IEEE-CPMT Advanced Technology Workshop on

Optoelectronic Packaging

June 29 - 30, 2011

McDonnell Douglas Engineering Auditorium
University of California - Irvine
Irvine, California

General Chair:
John Mazurowski
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Organizing Committee:
Dr. Benson Chan, Endicott Interconnect
Mr. Jack Cunningham, Oracle Labs
Dr. Boris Kolodin, GE Lighting Solutions
Dr. Chin Lee, University of California - Irvine
Dr. Kannan Raj, Oracle Labs
Mr. Alex Rosiewicz, EM4 Inc.

iMAPS

CPMT
IEEE COMPONENTS, PACKAGING AND MANUFACTURING TECHNOLOGY SOCIETY

Early Registration Deadline: June 17, 2011

No Host Hotel - see registration page.

IEEE-USA Government Fellowships:

Linking Science, Technology & Engineering Professionals with Government

(http://ieeeusa.org/policy/govfel/default.asp\)

Each year, IEEE-USA sponsors three government fellowships for qualified IEEE members. The fellows - chosen by the IEEE-USA Government Fellows Committee and confirmed by the Board - spend a year in Washington serving as advisers to the U.S. Congress and to key U.S. Department of State decision-makers. Known as either a Congressional Fellowship or an Engineering & Diplomacy Fellowship, this program links science, technology and engineering professionals with government, and provides a mechanism for IEEE's U.S. members to learn firsthand about the public policy process while imparting their knowledge and experience to policymakers.

2012 Application materials are now available online. **The deadline is March 18, 2011**

Application Kit for 2012 Congressional Fellowship

http://ieeeusa.org/policy/govfel/documents/cfappkit12_000.doc

Application Kit for 2012 Engineering & Diplomacy (State Department) Fellowship

http://ieeeusa.org/policy/govfel/documents/Stateappkit12_000.doc

2011 IEEE Phoenix Section Calendar

The calendar is updated by the Vice Chair on a rolling basis.

- April 2011
  - Student-Industry Mixer
  - MicroMouse registrations due to Southwest Area: TBD
  - Student papers due to Southwest Area: TBD
  - Southwest Area Spring meeting incl. Student Paper and MicroMouse contests: TBD
  - Nominating Committee formed for election of next year's Section officers
    - At least three members that are not Section officers (Chapter officers okay)

- May 2011
  - Student Branch reports to IEEE HQ and Student Activities Chair due: May 1, 2011
  - Call for Nominations issued by Nominating Committee

- June 2011
  - Review meeting schedules of Chapters
  - Nominations received by Nominating Committee

- July–August 2011
  - Summer break

- IEEE Congress August 19 -22, San Francisco

- September 2011
  - Student Branches send annual plan of activities to IEEE
  - Annual Banquet: Determine date, confirm hotel, speaker
  - Announcement of Student Paper Contest
  - Announcement of Student Scholarships
  - Call for nominations for awards
    - Categories: Young Engineer/GOLD, Engineer, Company, Educator

- October 2011
  - Announcement of Student Paper Contest
  - Announcement of Student Scholarships
  - Call for nominations for awards: see September
  - Southwest Area Fall meeting: TBD

- November 2011
  - Election of new officers
  - 2011 budget proposal
  - Start ad for Student Paper Contest and Scholarships
    - For dates see under February
  - Student Industry Mixer: TBD

- December 2011

- Report of Section activities for 2011
- Appoint chairs of Section committees
- Student Scholarship applications due: TBD
- Annual Banquet: Finalize speaker
- Annual Banquet: E-mail program

Phoenix Section Executive Committee Meeting

Venue: Phoenix Airport Hilton 2435 S 47th St, Phoenix, AZ, 85034 (map)
Tel.: 480-804-6017

More Info: Meetings are held on the first Tuesday of the month, 6–8 PM.
- Except for July & August

All interested IEEE members are welcome to attend.

Contact: Jim Hudson, Phoenix Section Chair
jim.hudson@srpnet.com

IEEE Phoenix Section Nomination of Officers

The IEEE Phoenix Section is seeking nominations for the following elected Section officer positions for the 2012 term:

- Chair
- Vice Chair
- Secretary
- Treasurer

Additionally, the Nominating Committee is seeking candidates for the following non-elected appointed standing committee chair positions for the 2012 term:

- Publicity
- Membership
- Student Activities
- Conferences
- Awards
- Inter-Society
- PACE (Professional Activities Committees for Engineers)
- TISP (Teacher In-Service Program)
- Web Master

Section officers must be IEEE members. Self-nominations are acceptable.

Please send nominations or any questions to Steve Rockwell (e-mail steve.rockwell@ieee.org), copying also Nominating Committee members Mike Andrews (e-mail: m.andrews@ieee.org) and Mohamed Arafa (e-mail: mohamed.arafa@intel.com).

Section members are urged to submit your nominations by no later than September 1.

Sincerely,
Steve Rockwell
Chair, Nominating Committee, Phoenix Section

Section Officer Job Descriptions

Section Chair

The Section Chair shall serve as Chair for all meetings of the Section, the Section Committee and the Section ExCom where such ExCom exists.

Roles:

- Preside at meetings of the Section Executive Committee
- Represent the Section at IEEE gatherings
- Represent the Section at Regional Committee Meetings and vote on issues on the basis of the best interest of IEEE

Vice Chair

The Section Vice Chair shall assist the Chair in the coordination of all Section activities. At the request of the Section Chair or in the absence of the Section Chair, the Section Vice Chair shall chair meetings of the Section, Section Committee or Section ExCom.

Secretary

The duties of the Section Secretary shall include correspondence, the keeping of the minutes of the Committee meetings, mailing notices, and submission of meeting and officer reports to the Member and Geographic Activities Department at the end of each year and such other duties as are assigned to him/her by the Chair.

Treasurer

The duties of the Section Treasurer shall include the development of a Section budget for approval by the Section, accounting of all Section funds, keeping financial records, and submitting the Financial Operations Report of the Section to the IEEE Staff Director, Financial Services.

Publicity

- Publish and distribute monthly section newsletter
- Maintain section email lists
- Support chapter publicity submissions to the the IEEE E-Notice system

Membership Chair

- Monitoring a current record of membership.
- Analyzing membership trends.
- Ensure adequate supplies of membership development materials available for distribution (chapter meetings, conferences, job fairs, etc.).
- Coordinating membership exhibits for local meetings and conferences, soliciting materials for exhibits, indentifying volunteers to staff booth.

Student Activities Chair

- Coordinate and support student chapters by working with the student chapter representatives and their faculty advisers.
- Organize the annual student paper competition
- Organize the annual student scholarship awards program

Conferences Chair

- Support and act as liaison between the section and locally held IEEE affiliated conferences
- Maintain calendar of IEEE related conference events on the section website calendar

Awards Chair

- Plan, coordinate, and organize the annual awards banquet

Inter-Society Chair

- Coordinate and act as liaison between section and other engineering or relevant organizational entities

PACE (Professional Activities Committees for Engineers) Chair

- Coordinate and support professional and career developmental activities

TISP (Teacher In-Service Program) Chair

- Coordinate the local TISP program

Web Master Chair

- Maintain and update the Section website as needed

"IEEE Phoenix Section Survey

IEEE Phoenix Section Executive Committee is requesting all IEEE Phoenix Section Members to provide their valuable inputs to help with continuous improvement of section activities. The survey can be accessed at www.ewh.ieee.org/r6/phoenix. Please download the survey and send by email to IEEE Phoenix Section Secretary, Dr. Chuck Weitzel, at c.weitzel@ieee.org. Your support in this matter will be greatly appreciated."

"IEEE Member Grade Advancement

All IEEE members are advised to look into advancing their IEEE membership to higher grades – senior member and Fellow. Please refer to www.ieee.org for additional information, requirements, and process for obtaining senior member and fellow grades. Please contact Dr. Vasudeva P. Atluri, Membership Chair, IEEE Phoenix Section at vpatluri@ieee.org for guidance and support."

IEEE Phoenix - Calendar of Events

You may access the IEEE Phoenix Section Calendar of Events at:

http://ewh.ieee.org/r6/phoenix/Calendar.htm

For inputs and updates to the Calendar, please contact the IEEE Phoenix Section Treasurer, Russ Kinner at 602-997-2353 or e-mail: r.kinner@ieee.org

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Phoenix Section LinkedIn Group

If you are interested in professional networking and shared Section related updates & discussions join the IEEE Phoenix Section Group on LinkedIn. Signing up only takes minutes and is free. A job board is available as well.